



## Material Content Data Sheet



<b>Sales Product Name</b>		IPP120N04S3-02		<b>Issued</b>		29. August 2013			
<b>MA#</b>		MA000361814							
<b>Package</b>		PG-TO220-3-1		<b>Weight*</b>		2040.72 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	12.237	0.60	0.60	5997	5997	
leadframe	non noble metal	iron	7439-89-6	1.407	0.07		689		
	inorganic material	phosphorus	7723-14-0	0.422	0.02		207		
	non noble metal	copper	7440-50-8	1404.801	68.84	68.93	688385	689281	
wire	non noble metal	aluminium	7429-90-5	7.354	0.36	0.36	3604	3604	
encapsulation	organic material	carbon black	1333-86-4	8.778	0.43		4302		
	plastics	epoxy resin	-	96.562	4.73		47318		
	inorganic material	silicondioxide	60676-86-0	479.882	23.52	28.68	235154	286774	
leadfinish	non noble metal	tin	7440-31-5	21.462	1.05	1.05	10517	10517	
plating	non noble metal	nickel	7440-02-0	0.244	0.01		120		
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.01	0	120	
solder	noble metal	silver	7440-22-4	0.189	0.01		93		
	non noble metal	tin	7440-31-5	0.151	0.01		74		
	non noble metal	lead	7439-92-1	7.225	0.35	0.37	3540	3707	
*deviation	< 10%					Sum in total:	100.00		1000000

### Important Remarks:

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